









PRODUCT DATASHEET



- ► PLCC2 Top View
- ➤ 3528+Lens 3.6t Series
- ► Red (622nm)

NOR51S27BS



3528+Lens Series





3528 + Lens Series

APPLICATIONS:

- **LED Display**
- Indicator
- Traffic Display
- **Decoration Lighting**

FEATURES:

- Package: PLCC2 Black Face SMT Package with Lens
- Forward Current: 20mA Forward Voltage (typ.): 2.0V
- Luminous Intensity (typ.): 3440mcd@20mA
- Colour: Red
- Wavelength: 622nm Viewing angle: 30°
- **Materials:**
 - Die: AlGaInP
 - Resin: Epoxy (Water Clear)
 - L/F Finish: Ag Plated
- Operating Temperature: -40~+80°C
- **Storage Temperature:** -40~+85°C
- **Grouping parameters:**
 - Forward voltage
 - Luminous intensity
 - **Dominant Wavelength**
- Soldering methods: Reflow soldering Preconditioning: acc. to JEDEC Level 3
- Packing: 12mm tape with max.2000pcs/reel, ø330mm (13'')



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	30	mA
Peak Forward Current Duty 1/8@1KHz	I _{FP}	125	mA
Reverse Voltage	V _R	5	V
Reverse Current @5V	I _R	10	μΑ
Power Dissipation	P _D	75	mW
Operating Temperature	T _{OPR}	-40~+80	°C
Storage Temperature	T _{STG}	-40~+85	°C

Electrical & Optical Characteristics (Ta=25°C)

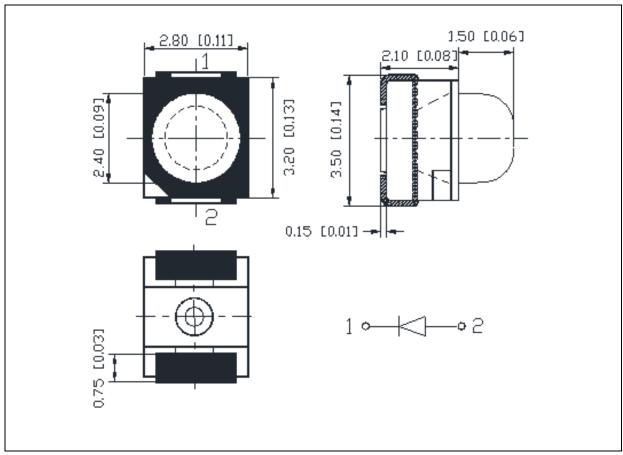
Parameter	Cumbal	Values			Unit	Test
Parameter	Symbol	Min.	Тур.	Max.	Offic	Condition
Forward Voltage	V _F	1.7	2.0	2.5	V	I _F =20mA
Luminous Intensity	lv	2000	3440	6800	mcd	I _F =20mA
Dominant Wavelength	λ_{D}	615	622	630	nm	I _F =20mA
Peak Wavelength	λ_{P}		630		nm	I _F =20mA
Spectral Half Bandwidth	Δλ		21		nm	I _F =20mA
Viewing Angle	2θ _{1/2}		30		deg	I _F =20mA

^{1.} Luminous intensity (Iv) $\pm 15\%$, Forward Voltage (V_F) $\pm 0.1V$, Viewing angle($2\theta_{1/2}$) $\pm 5\%$



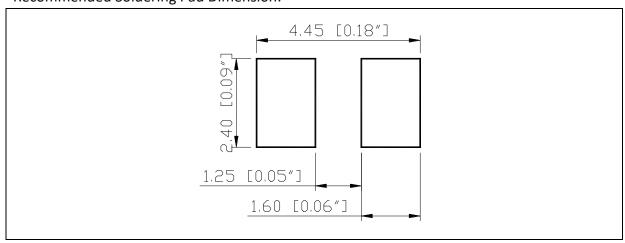
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



BINNING GROUPS:

Forward Voltage Classifications (I_F = 20mA):

Code	Min.	Max.	Unit
	1.7	2.5	V

Luminous Intensity Classifications (I_F = 20mA):

Code	Min.	Max.	Unit
W	2000	2500	
X	2500	3200	
Υ	3200	4000	mcd
Z	4000	5200	
a	5200	6800	

Wavelength Classifications (I_F = 20mA):

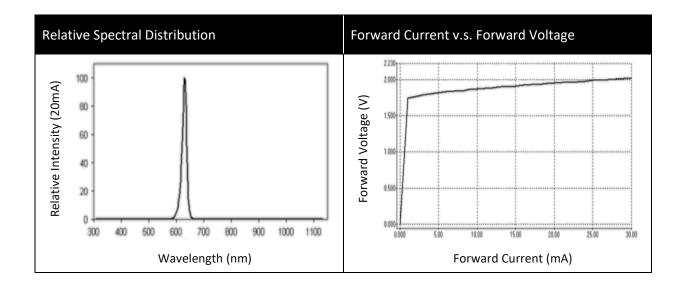
Code	Min.	Max.	Unit
S	615	620	
t	620	625	nm
u	625	630	

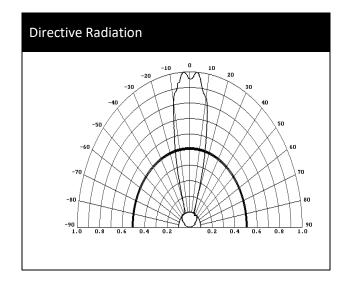
Example Binning Information on Label:

Code	Vf (V)	Iv (mcd)	λd (nm)	Test Condition
☐ Yt20	1.7~2.5	3200~4000	620~625	nm



ELECTRO-OPTICAL CHARACTERISTICS:

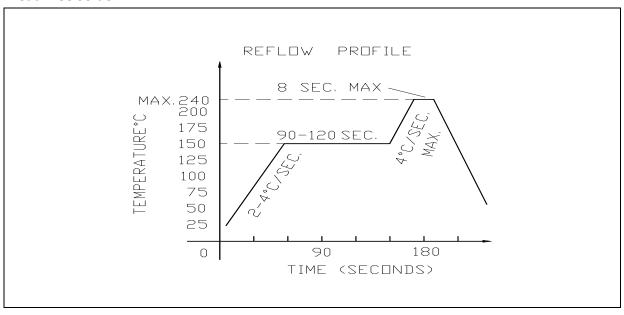






RECOMMENDED SOLDERING PROFILE:

Lead-free Solder:



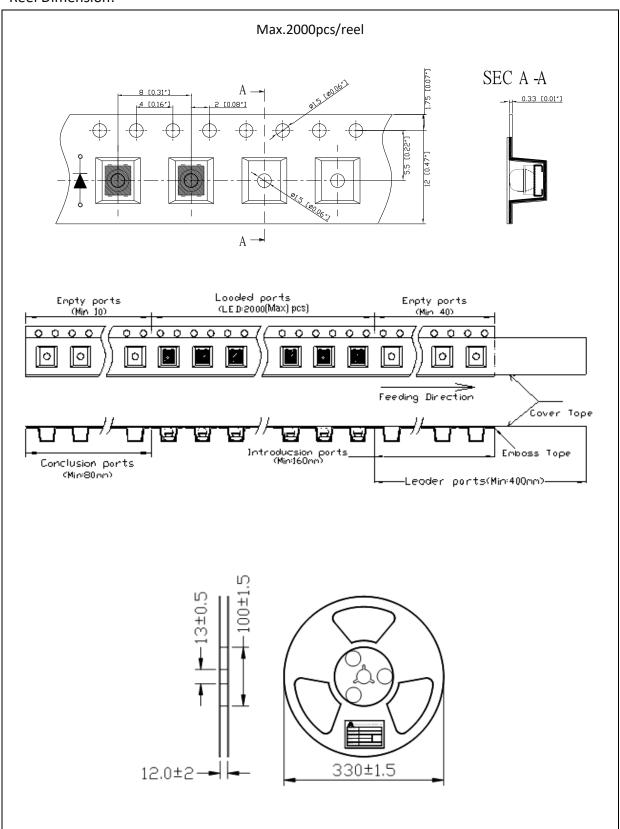
Note:

- 1. Maximum reflow soldering: 1 time.
- 2. The maximum soldering temperature is 240°C.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

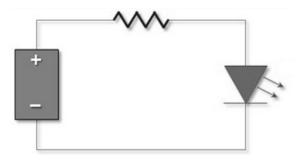
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	30/04/2020	Datasheet set-up.